



AMENDMENT UNDER 37 CFR 1.116
EXPEDITED PROCEDURE-
EXAMINING GROUP 2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Hua Ji
Assignee: Mosel Vitelic, Inc.
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench
Serial No.: 10/080,468 Filing Date: February 22, 2002
Examiner: Anh D. Mai Group Art Unit: 2814
Docket No.: M-12589US

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February 7, 2003

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RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated November 20, 2002, Applicant respectfully requests entry of the following amendments to the above-identified application under 37 C.F.R. § 1.116.

IN THE SPECIFICATION

Please replace the following paragraph. A marked-up version showing the changes is included as Attachment A.

Please replace the paragraph on page 8, line 3 through line 22, with the following replacement paragraph:

In addition to a reduced oxygen to silane ratio, the method of the present invention allows for low etch-to-deposition (E/D) ratios, corresponding to greater gap-fill capability. An E/D ratio is defined by the equation: